ABSTRACT

METHOD FOR CLEANING ANODIZED PARTS OF SEMICONDUCTOR EQUIPMENT

Disclosed is a method for cleaning anodized aluminum parts of semiconductor equipment using ultrasonic waves in combination with a specially formulated cleaning solution. The method provided efficient cleaning while preserving the integrity of the anodized layer, reducing labor costs, and increased time of recycled use of the cleaned parts by 30-50%.

Figure 3a, 3b and 3c